

STRUCTURE
PRODUCT NAME
FUNCTION
FEATURE

Silicon monolithic integrated circuit

BU9798GUW

LCD control driver for segment type LCD display

- LCD drive output : Common output : 4, Segment output : 49
- built-in Display data RAM (DDRAM) : RAM: 49*4 =196 bit
- 3-wire Serial interface(SD, SCL, CSB)
- built-in Oscillator circuit
- built-in LCD Voltage Generator circuit: support 1/3 Bias, 1/3 or 1/4 Duty, 1/1 Bias, 1/1Duty (Static Driving)
Built-in Buffer AMP, Built-in regulator (3.2, 3.3, 3.4, 4.4, 4.5, 4.6, 5.0V)
- Support Split Supply for Logic (VDD) and LCD (VLCD)
- Support two output mode SEG/GPO (SEG15~45)
- built-in LED driver
- Support two output mode SEG/LED driver (SEG46~48)
- Support PWM source select, external clock or internal clock (12bit / 8bit mode selectable)
- Low power consumption
- Support standby mode
- built-in Power-on Reset circuit
- No external component
- Support blink function (Blink frequency 1.6, 2.0, 2.6, 4.0 Hz selectable)
- Operating power supply: 1.8~3.6V
- LCD drive power supply voltage : 3.3~5.5V

○ **Absolute maximum ratings (VSS = 0V)**

Parameter	Symbol	Rated values	Unit	Remarks
Power supply voltage 1	VDD	-0.3 ~ +4.5	V	Power supply
Power supply voltage 2	VLCD	-0.5 ~ +7.0	V	LCD drive voltage
Allowable loss	Pd	0.8* ¹	W	
Input voltage range	VIN	-0.5 ~ VDD+0.5	V	
Operational temperature range	Topr	-30 ~ +75	°C	
Storage temperature range	Tstg	-55 ~ +125	°C	
Output current	Iout1	5	mA	SEG ouput
	Iout2	5	mA	COM ouput
	Iout3	10	mA	GPO ouput
	Iout4	50	mA	LED ouput

*1 When use more than Ta=25 degree, subtract 8.0mW per degree. (using ROHM standard board)
(board size : 114.3mm×76.2mm×1.6mm material: FR4 board copper foil: land pattern only)

○ **Recommend operating conditions (Ta=-30~+75degree, VSS = 0V)**

Parameter	Symbol	MIN	TYP	MAX	Unit	Remarks
Power supply voltage 1	VDD	1.8	-	3.6	V	Power supply
Power supply voltage 2	VLCD	3.3	-	5.5	V	For LCD drive
LED Power supply voltage	VLED	1.0	-	VLCD	V	LED drive voltage
Output current	Iout4	-	-	25	mA	At one LED port
	Iout4	-	-	75	mA	At all LED port

○ This product is not designed against radioactive ray.

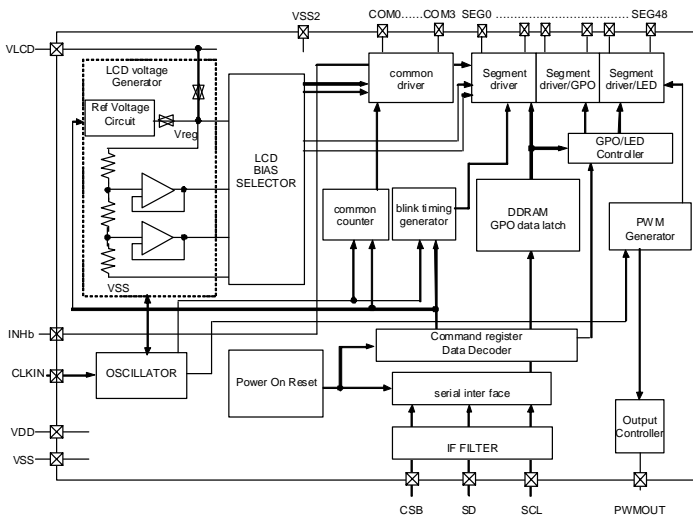
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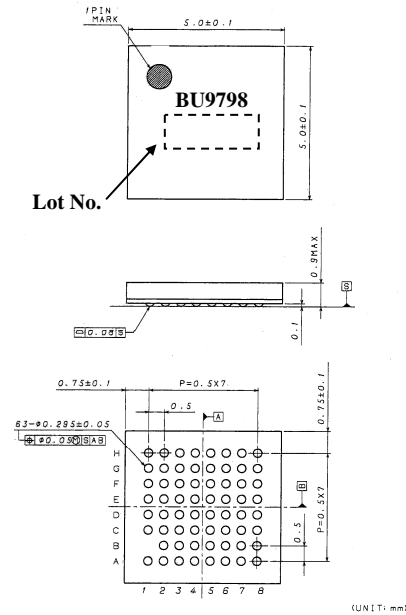
The Japanese version of this document is the formal specification. A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document, formal version takes priority.

○Block diagrams



○Outline drawing



○ Electrical Characteristics

(Ta=−30~75degree, VDD=1.8V~3.6V, VLCD=3.3V~5.5V, VSS=0 ; unless otherwise specified)

PKG:VBGA063W050
Drawing No. EX861-5001

Parameter	Symbol	Limit			Unit	Condition
		MIN	TYP	MAX		
“H” level input voltage	VIH	0.8VDD	-	VDD	V	SD, SCL, CSB, CLKIN, TEST1, INHb
“L” level input voltage	VIL	VSS	-	0.2VDD	V	SD, SCL, CSB, CLKIN, TEST1, INHb
Hysteresis width	VH	-	0.2	-	V	SCL, INHb, VDD=3.3V, Ta=25degree
“H” level input current	I _{IH1}	-	-	5	uA	SD, SCL, CSB, CLKIN, INHb, VI=3.6V
“L” level input current	I _{IL1}	-5	-	-	uA	SD, SCL, CSB, CLKIN, INHb, TEST1, VI=0V
“H” level output voltage (*1) (*3)	VOH1	VLCD-0.4	-	-	V	Iload=-50uA, VLCD=5.0V, SEG0~48, In case, internal regulator do not use
	VOH2	VLCD-0.4	-	-	V	Iload=-50uA, VLCD=5.0V, COM0~3, In case, internal regulator do not use
	VOH3	VLCD-0.6	-	-	V	Iload=-1mA, VLCD=5.0V, SEG15~45(GPO mode) In case, internal regulator do not use
	VOH4	VDD-0.6	-	-	V	Iload=-1mA, VDD=3.3V, PWMOUT
“L” level output voltage (*3)	VOL1	-	-	0.4	V	Iload= 50uA, VLCD=5.0V, SEG0~48
	VOL2	-	-	0.4	V	Iload= 50uA, VLCD=5.0V, COM0~3
	VOL3	-	-	0.5	V	Iload=1mA, VLCD=5.0V, VDD=3.3V SEG15~45(GPO mode), PWMOUT
	VOL4	-	0.11	0.5	V	Iload=20mA, VLCD=5.0V SEG46~48(LED drive mode)
Supply current (*2)	IstVDD	-	3	10	uA	Input terminal ALL'L, Display off, Oscillation off
	IstVLCD	-	0.5	5	uA	Input terminal ALL'L, Display off, Oscillation off
	IVDD1	-	8	15	uA	VDD=3.3V, Ta=25degree, 1/3bias, fFR=64Hz, PWM generate off, All output pin open
	IVDD2	-	90	130	uA	VDD=3.3V, Ta=25degree, 1/3bias, fFR=64Hz, PWM Frequency=500Hz setting, output pin open
	IVLCD1	-	10	15	uA	VLCD=5.0V, Ta=25degree, 1/3bias, fFR=64Hz, internal regulator do not use, LED drive mode off, All output pin open
	IVLCD2	-	25	40	uA	VLCD=5.0V, Ta=25degree, 1/3bias, fFR=64Hz, using internal regulator, LED drive mode off, All output pin open
IVLCD3	-	30	48	uA	VLCD=5.0V, Ta=25degree, 1/3bias, fFR=64Hz, using internal regulator, PWM Frequency=500Hz setting, output pin open	

*1 In case, internal regulator do not use. When you use internal regulator, please add load regulation specified at page3

*2 In case, power save mode 1 and frame inversion setting *3 Iload : In case, load current from only one port

○ Oscillation Frequency Characteristics (Ta=-30~75degree, VDD=1.8V~3.6V, VLCD=3.3V~5.5V, VSS=0 ; unless otherwise specified)

Parameter	Symbol	Limit			Unit	Condition
		MIN	TYP	MAX		
Frame frequency 1	fFR1	57.6	64	70.4	Hz	VDD=3.3V, Ta=25degree, fFR=64Hz setting
Frame frequency 2	fFR2	51.2	64	73.0	Hz	VDD=2.5~3.6V fFR=64Hz setting
Frame frequency 3	fFR3	45.0	-	64	Hz	VDD=1.8~2.5V fFR=64Hz setting
CLKIN input frequency	fCLK	-	2	4	MHz	

○ Load regulation (Ta=-30~75degree, VDD=1.8V~3.6V, VLCD=3.3V~5.5V, VSS=0 ; unless otherwise specified)

Parameter	Symbol	Limit			Unit	Condition
		MIN	TYP	MAX		
Output voltage 1	Vreg1	4.25	4.5	4.70	V	4.5V setting (VLCD=5.5V, Ta=-30~75degree)
Output voltage 2	Vreg2	4.38	4.5	4.62	V	4.5V setting (VLCD=5.5V, Ta=25degree)
Load Regulation (**)	Δ Vreg	-	-	0.3	V	Iout = -300uA

Caution : Please use regulator at "Regulator output voltage < VLCD - 0.5V"

** Internal regulator unit only.

○ MPU interface Characteristics (Ta=-30~75degree, VDD=1.8V~3.6V, VLCD=3.3V~5.5V, VSS=0)

Parameter	Symbol	Limit			Unit	Condition
		MIN	TYP	MAX		
Input rise time	tr	-	-	50	ns	
Input fall time	tf	-	-	50	ns	
SCL cycle time	tSCYC	250	-	-	ns	
"H" SCL pulse width	tSHW	50	-	-	ns	
"L" SCL pulse width	tSLW	50	-	-	ns	
SD setup time	tSDS	50	-	-	ns	
SD hold time	tSDH	50	-	-	ns	
CSB setup time	tCSS	50	-	-	ns	
CSB hold time	tCSH	50	-	-	ns	
"H" CSB pulse width	tCHW	50	-	-	ns	

○ Terminal number/name

A1	CSB	B1	(NC)	C1	VSS1	D1	VLCD	E1	COM2	F1	SEG0	G1	SEG2	H1	SEG4
A2	PWMOUT	B2	CLKIN	C2	SDA	D2	VDD	E2	COM0	F2	SEG1	G2	SEG3	H2	SEG5
A3	SEG48	B3	VSS2	C3	SCL	D3	INH	E3	COM1	F3	SEG6	G3	SEG7	H3	SEG9
A4	SEG46	B4	SEG44	C4	SEG45	D4	SEG47	E4	COM3	F4	SEG10	G4	SEG8	H4	SEG11
A5	SEG43	B5	SEG40	C5	SEG42	D5	SEG31	E5	SEG15	F5	SEG13	G5	SEG12	H5	SEG14
A6	SEG41	B6	SEG39	C6	SEG38	D6	SEG29	E6	SEG26	F6	SEG22	G6	SEG17	H6	SEG16
A7	SEG37	B7	SEG35	C7	SEG33	D7	SEG28	E7	SEG24	F7	SEG23	G7	SEG19	H7	SEG18
A8	SEG36	B8	SEG34	C8	SEG32	D8	SEG30	E8	SEG27	F8	SEG25	G8	SEG21	H8	SEG20

Cautions on use

(1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) Operating conditions

These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are guaranteed under the conditions of each parameter.

(3) Reverse connection of power supply connector

The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.

(4) Power supply line

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. In this regard, or the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern from the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner.

Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(5) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.

(6) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.

(7) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.

(8) Inspection with set PCB

On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.

(9) Input terminals

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.

(10) Ground wiring pattern

If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.

(11) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

(12) No Connecting input terminals

In terms of extremely high impedance of CMOS gate, to open the input terminals causes unstable state. And unstable state brings the inside gate voltage of p-channel or n-channel transistor into active. As a result, battery current may increase. And unstable state can also causes unexpected operation of IC. So unless otherwise specified, input terminals not being used should be connected to the power supply or GND line.

(13) Rush current

When power is first supplied to the CMOS IC, it is possible that the internal logic may be unstable and rush current may flow instantaneously. Therefore, give special condition to power coupling capacitance, power wiring, width of GND wiring, and routing of connections.

Notes

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